



DOCKET NO. END920010002US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ray *et al.*

Examiner: Nguyen, Ha T

Serial No.: 09/779,812 ✓

Art Unit: 2812

Filed: 2/08/01

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For: LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE

Commissioner for Patents  
Washington D.C. 20231

Sir:

At the time of filing the above-mentioned patent application, Applicants submitted an Information Disclosure Statement which listed the reference of Australian Patent AU-B-68124/90 (Ogashiwa, published 07/91). Applicants also submitted a copy of this reference with the originally filed present patent application, but have recently discovered that several pages were missing from said originally submitted copy of this reference. Applicants are therefore submitting herewith, a complete copy, with no pages missing, of this reference. Applicants respectfully request that the Examiner consider this reference in its entirety in reviewing the present patent application in light of the prior art.

Date:

2/21/03

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09/779,812

2812



<b>TRANSMITTAL LETTER</b> (General - Patent Pending)	Docket No. <b>END920010002US1</b>
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In Re App. No. Of: Ray et al.

Serial No. 09/779,812	Filing Date 2/8/2001	Examiner Nguyen, Ha T.	Group Art Unit 2812
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Title: **LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

**Amendment**

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of \_\_\_\_\_ is attached.
- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457(IBM)** as described below. A duplicate copy of this sheet is enclosed.
  - ☐ Charge the amount of \_\_\_\_\_
  - ☒ Credit any overpayment.
  - ☒ Charge any additional fee required.

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*Jack P. Friedman*  
Signature

Dated: 2/20/2003

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I certify that this document and fee is being deposited on 2/20/2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.
<i>Kim Dwileski</i> Signature of Person Mailing Correspondence
<b>Kim Dwileski</b> Typed or Printed Name of Person Mailing Correspondence

CC: